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Reference # ARI-A-7406



Aries' Machined High-Frequency Center Probe Test Sockets Now Available in Pitch Sizes Down to 0.30 mm

Ideal for wide variety of BGA, CSP and MLF packages

Bristol, Pa. January 2011 – Aries Electronics, an international manufacturer of standard, programmed and custom interconnection products, now offers machined high-frequency center probe test sockets to accommodate IC devices with a lead pitch of 0.30 mm. With very low inductance and capacitance, the sockets are ideal for a wide variety of BGA (ball grid array), CSP (chip scale package) and MLF (micro land frame) packages.

Reduced inductance, increased board density and finer pitch array packages are made possible thanks to a four-point crown or sharp point gold plated 0.30 mm pitch probe pin, spring and flanged bottom pin, which contacts the tail of the probe pin to shorten the signal path. A signal path of just 0.077 inches (1.96 mm) allows for minimal signal loss and higher bandwidth capacity with the new Aries' machined high-frequency sockets.

The solderless pressure mount spring probes allow easy mounting of the socket to a test board and device solder ball or pad, while socket locating posts ensure accurate positioning of the socket to the board. The sockets are equipped with chip guides to allow exact device location and four-point edge male contacts for precise mating of the device. The socket's small footprint ensures maximum use of the test board area for increased efficiency.

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Spring loaded contacts, made of gold-plated beryllium copper, provide a high life cycle of up to 500,000 cycles. Socket body material is Torlon PAI and all hardware is stainless steel.

The socket's contact forces are 15 g per contact on a 0.30 mm to 0.35 mm pitch, 16 g per contact on a 0.40 mm to 0.45 mm pitch and 25 g per contact on a 0.50 mm pitch or larger. Contact resistance is less than 40 milliohms. Probe self-inductance on the new socket is 0.51 nH for large probes and 0.59 nH for small probes.

The socket accepts solder ball sizes from 0.15 mm to 0.93 mm. Insertion loss is 1 dB to 10.1 GHz for a larger probe at 0.80 mm pitch and 1 dB to 18.7 GHz for a smaller probe at 0.50 mm pitch.

Pricing for a 50-position socket rated to 5 GHz starts at \$975. Delivery is twenty working days ARO and approval of drawing.

For additional information, contact Aries Electronics Inc., 2609 Bartram Road, Bristol, Pa. 19007-6810; Tel: 215-781-9956; Fax: 215-781-9845; Email: info@arieselec.com; Web: <http://www.arieselec.com>, Data sheet #24010—
http://www.arieselec.com/Web_Data_Sheets/24010/24010.htm.
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UPCOMING TRADESHOW: BiTS Workshop, March 6-9, 2011 – Mesa, AZ

READER SERVICE INQUIRIES: Please forward all reader service inquiries to Frank Folmsbee, Aries Electronics Inc., 2609 Bartram Road, Bristol, Pa. 19007-6810.

EDITORS NOTE: Headquartered in Bristol, Pa., Aries Electronics Inc. manufactures an extremely broad range of custom and standard interconnection and packaging products for electronics. Industry leading products include Zero Insertion Force (ZIF) test sockets for DIP, PGA, PLCC and SOIC devices; the "intelligent" Correct-A-Chip™ product line; adapters and connectors; several patented concepts for BGA (ball grid array) and LGA (land grid array) sockets; and an extensive array of high frequency test and burn in sockets. The company also specializes in meeting custom requirements for its customers.